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Substitute for Form 1449B/PTO  <b>INFORMATION DISCLOSURE  STATEMENT BY APPLICANT</b>  <i>(use as many sheets as necessary)</i>				<b>Complete If Known</b>	
				Application Number	Unknown
				Filing Date	Herewith
				First Named Inventor	Wan-Thai Hsu, et al.
				Group Art Unit	Unknown
				Examiner Name	Unknown
Sheet	2	of	2	Attorney Docket Number	UOM 0210 PUSP 1
<b>OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS</b>					
Examiner Initials	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.			T <sup>2</sup>
		HSU, WAN-THAI, ET AL., A Sub-Micron Capacitive Gap Process For Multiple-Metal-Electrode Lateral Micromechanical Resonators, Technical Digest, IEEE Int. Micro Electromechanical Systems Conf., Interlake, Switzerland, January 21-25, 2001, pp. 349-352.			
		HSU, WAN-THAI, ET AL., Mechanically Temperature-Compensated Flexural-Mode Micromechanical Resonators, Technical Digest, IEEE Int. Electron Devices Meeting, San Francisco, California, Dec. 11-13, 2000, pp. 399-402.			
		CLARK, JOHN R., ET AL., High-Q VHF Micromechanical Contour-Mode Disk Resonators, Technical Digest, IEEE Int. Electron Devices Meeting, San Francisco, California, December 11-13, 2000, pp. 493-496.			
		CLARK, JOHN R., ET AL., Measurement Techniques For Capacitively-Transduced VHF-to-UHF Micromechanical Resonators, Digest of Technical Papers, the 11 <sup>th</sup> Int. Conf. on Solid-State Sensors & Actuators, Munich, Germany, June 10-14, 2001, pp. 1118-1121.			
		C. T.-C. NGUYEN, "Micromachining technologies for miniaturized communication devices," Proceedings of SPIE: Micromachining and Microfabrication, Sept. 20-22, 1998, pgs. 24-38			
		T. HIRANO et al., "Design, Fabrication, and Operation of Submicron Gap Comb-Drive Microactuators," Journal of Microelectromechanical Systems, March 1992, No. 1, pgs. 52-59			
		J.R. TUCKER et al., "Nanoscale FETs and STM Lithography," University of Illinois, 1995, pgs. 425-434			
		C. T.-C. Nguyen, "High-Q Micromechanical Oscillators and Filters For Communications," Int'l Symposium on Circuits and Systems, June 9-12, 1997, pgs. 2825-2828			
		K. TANAKA, "Nanotechnology towards the 21 <sup>st</sup> Century," Thin Solid Films, 1999, pgs. 120-125			

Examiner Signature		Date Considered	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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